

Phase Control Thyristors (Hockey PUK Version), 500 A



TO-200AB (A-PUK)

PRODUCT SUMMARY				
Package	TO-200AB (A-PUK)			
Diode variation	Single SCR			
I _{T(AV)}	500 A			
V _{DRM} /V _{RRM}	400 V, 600 V			
V_{TM}	1.35 V			
I _{GT}	90 mA			
T_J	-40 °C to 150 °C			

FEATURES

- · Center amplifying gate
- Metal case with ceramic insulator
- International standard case TO-200AB (A-PUK)



- Extended temperature range
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

- DC motor controls
- Controlled DC power supplies
- AC controllers

MAJOR RATINGS AND CHARACTERISTICS						
PARAMETER	TEST CONDITIONS	VALUES	UNITS			
1		500	A			
I _{T(AV)}	T _{hs}	80	°C			
		1130	Α			
I _{T(RMS)}	T _{hs}	25	°C			
	50 Hz	7200	^			
I _{TSM}	60 Hz	7500	А			
124	50 Hz	260	kA ² s			
l ² t	60 Hz	230	KA-S			
V _{DRM} /V _{RRM}		400 to 600	V			
tq	Typical	100	μs			
T _J		-40 to 150	°C			

ELECTRICAL SPECIFICATIONS

VOLTAGE RATINGS								
TYPE NUMBER	VOLTAGE CODE	V _{DRM} /V _{RRM} , MAXIMUM REPETITIVE PEAK AND OFF-STATE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK VOLTAGE V	$\begin{array}{l} I_{DRM}/I_{RRM} \; MAXIMUM \\ AT \; T_J = T_J \; MAXIMUM \\ mA \end{array}$				
VS-ST280CHC	04	400	500	75				
V3-312000HC	06	600	700	75				



ABSOLUTE MAXIMUM RATINGS	S					
PARAMETER	SYMBOL		VALUES	UNITS		
Maximum average on-state current	L	180° condu	180° conduction, half sine wave			Α
at heatsink temperature	I _{T(AV)}	double side	(single side) co	oled	80 (110)	°C
Maximum RMS on-state current	I _{T(RMS)}	DC at 25 °C	heatsink tempe	erature double side cooled	1130	
		t = 10 ms	No voltage		7200	
Maximum peak, one-cycle	L	t = 8.3 ms	reapplied		7500	A kA ² s
non-repetitive surge current	I _{TSM}	t = 10 ms	100 % V _{RRM}	Sinusoidal half wave, initial $T_J = T_J$ maximum	6000	
		t = 8.3 ms	reapplied		6300	
Maximum I ² t for fusing	l ² t	t = 10 ms	No voltage reapplied		260	
		t = 8.3 ms			235	
		t = 10 ms			180	
		t = 8.3 ms	reapplied		165	
Maximum I ² √t for fusing	I ² √t	t = 0.1 to 10	ms, no voltage	reapplied	2600	kA²√s
Low level value of threshold voltage	V _{T(TO)1}	(16.7 % x π	$x I_{T(AV)} < I < \pi x$	$I_{T(AV)}$), $T_J = T_J$ maximum	0.84	V
High level value of threshold voltage	V _{T(TO)2}	$(I > \pi \times I_{T(AV)})$	$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ maximum}$			V
Low level value of on-state slope resistance	r _{t1}	(16.7 % x π	$(16.7 \% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}), T_J = T_J \text{ maximum}$			mΩ
High level value of on-state slope resistance	r _{t2}	$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ maximum}$			0.47	11122
Maximum on-state voltage	V_{TM}	$I_{pk} = 1000 \text{ A}, T_J = T_J \text{ maximum}, t_p = 10 \text{ ms sine pulse}$			1.35	V
Maximum holding current	I _H	T 05 °C	anada ayanlı 1	O V registive lead	600	A
Maximum (typical) latching current	ΙL	T _J = 25 °C, anode supply 12 V resistive load 1000 (300)			1000 (300)	- mA

SWITCHING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum non-repetitive rate of rise of turned-on current	dl/dt	Gate drive 20 V, 20 Ω , $t_r \le 1~\mu s$ $T_J = T_J$ maximum, anode voltage $\le 80~\%~V_{DRM}$	1000	A/μs
Typical delay time	t _d	Gate current 1 A, $dl_g/dt = 1 A/\mu s$ V_d 0.67 % V_{DRM} , $T_J = 25 °C$	1.0	5
Typical turn-off time	t _q	$\begin{array}{l} I_{TM}=300~A,~T_J=T_J~maximum,~dl/dt=20~A/\mu s,\\ V_R=50~V,~dV/dt=20~V/\mu s,~gate~0~V~100~\Omega,~t_p=500~\mu s \end{array}$	100	μs

BLOCKING						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNIT S		
Maximum critical rate of rise of off-state voltage	dV/dt	T _J = T _J maximum linear to 80 % rated V _{DRM}	500	V/µs		
Maximum peak reverse and off-state leakage current	I _{RRM} , I _{DRM}	$T_J = T_J$ maximum, rated V_{DRM}/V_{RRM} applied	75	mA		



TRIGGERING						
PARAMETER	SYMBOL	TE	ST CONDITIONS	VALUES		UNITS
PANAMETER	STIMBOL	16	ST CONDITIONS	TYP.	MAX.	UNITS
Maximum peak gate power	P _{GM}	$T_J = T_J$ maximum,	$t_p \leq 5 \ ms$	10	0.0	W
Maximum average gate power	P _{G(AV)}	$T_J = T_J$ maximum,	f = 50 Hz, d% = 50	2	.0	VV
Maximum peak positive gate current	I _{GM}	$T_J = T_J$ maximum,	$t_p \leq 5 \ ms$	3	.0	Α
Maximum peak positive gate voltage	+ V _{GM}	T - T maximum	+ < 5 mg	2	0	V
Maximum peak negative gate voltage	- V _{GM}	$T_J = T_J$ maximum,	l _p ≤ 5 IIIS	5.0		V
DC gate current required to trigger	I _{GT}	T _J = - 40 °C		180	-	
		T _J = 25 °C		90	150	mA
		T _J = 150 °C	Maximum required gate trigger/ current/voltage are the lowest	30	-	
		T _J = - 40 °C	value which will trigger all units 12 V anode to cathode applied	2.9	-	
DC gate voltage required to trigger	V_{GT}	T _J = 25 °C	12 v anode to cathode applied	1.8	3.0	V
		T _J = 150 °C		1.0	-	
DC gate current not to trigger	I _{GD}	T T	Maximum gate current/voltage not to trigger is the maximum value which will not trigger any unit with rated V _{DRM} anode to cathode applied	1	0	mA
DC gate voltage not to trigger	V_{GD}	$T_J = T_J$ maximum		0.30		V

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum operating junction and storage temperature range	T _J , T _{Stg}		- 40 to 150	°C		
Maximum thermal resistance,	D	DC operation single side cooled	0.17			
junction to heatsink	R _{thJ-hs}	DC operation double side cooled	0.08	K/W		
Maximum thermal resistance,	Б	DC operation single side cooled	0.033	r√ vv		
case to heatsink	R _{thC-hs}	DC operation double side cooled	0.017			
Mounting force, ± 10 %			4900 (500)	N (kg)		
Approximate weight			50	g		
Case style		See dimensions - link at the end of datasheet TO-200AB		-PUK)		

△R _{thJ-hs} CONDUCTION								
CONDUCTION ANGLE	SINUSOIDAL	CONDUCTION	RECTANGULAR	CONDUCTION	TEST CONDITIONS	UNITS		
CONDUCTION ANGLE	SINGLE SIDE	DOUBLE SIDE	SINGLE SIDE	DOUBLE SIDE	TEST CONDITIONS	UNITS		
180°	0.016	0.017	0.011	0.011	T _J = T _J maximum	K/W		
120°	0.019	0.019	0.019	0.019				
90°	0.024	0.024	0.026	0.026				
60°	0.035	0.035	0.036	0.037				
30°	0.060	0.060	0.060	0.061				

Note

[•] The table above shows the increment of thermal resistance R_{thJ-hs} when devices operate at different conduction angles than DC



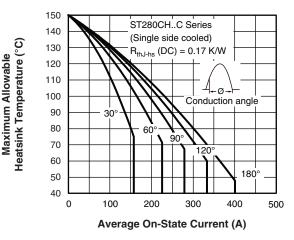
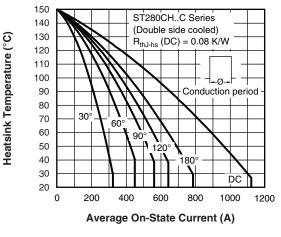


Fig. 1 - Current Ratings Characteristics



Maximum Allowable

Fig. 4 - Current Ratings Characteristics

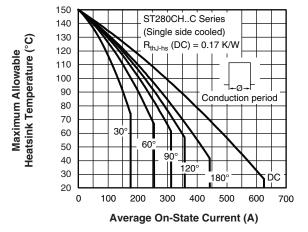


Fig. 2 - Current Ratings Characteristics

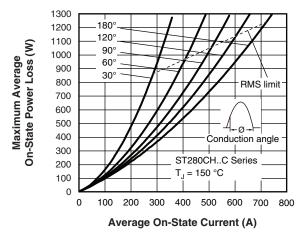


Fig. 5 - On-State Power Loss Characteristics

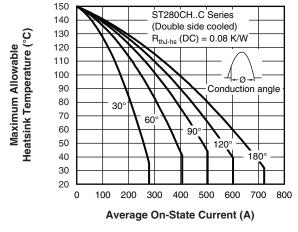


Fig. 3 - Current Ratings Characteristics

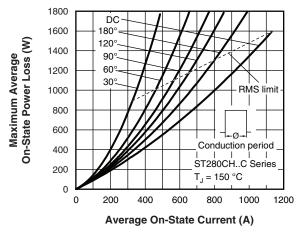


Fig. 6 - On-State Power Loss Characteristics

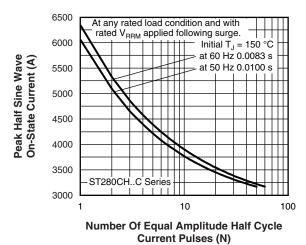


Fig. 7 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

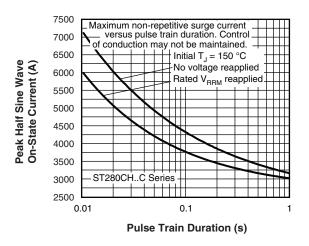


Fig. 8 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

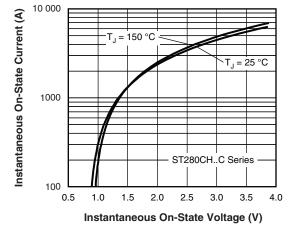


Fig. 9 - On-State Voltage Drop Characteristics

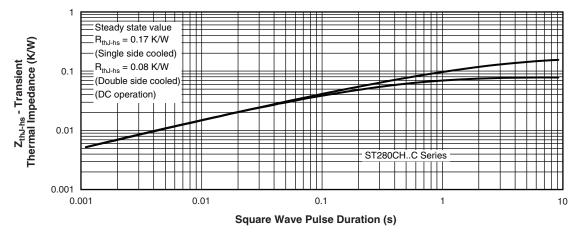


Fig. 10 - Thermal Impedance Z_{thJ-hs} Characteristics

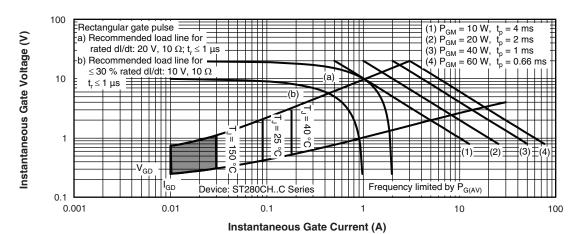
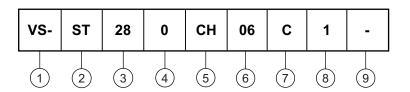


Fig. 11 - Gate Characteristics

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Thyristor

3 - Essential part number

4 - 0 = Converter grade

5 - CH = Ceramic PUK, high temperature

6 - Voltage code x 100 = V_{RRM} (see Voltage Ratings table)

7 - C = PUK case TO-200AB (A-PUK)

8 - 0 = Eyelet terminals (gate and auxiliary cathode unsoldered leads)

1 = Fast-on terminals (gate and auxiliary cathode unsoldered leads)

2 = Eyelet terminals (gate and auxiliary cathode soldered leads)

3 = Fast-on terminals (gate and auxiliary cathode soldered leads)

9 - Critical dV/dt: • None = 500 V/µs (standard selection)

• L = 1000 V/μs (special selection)

LINKS TO RELATED DOCUMENTS			
Dimensions	www.vishay.com/doc?95074		

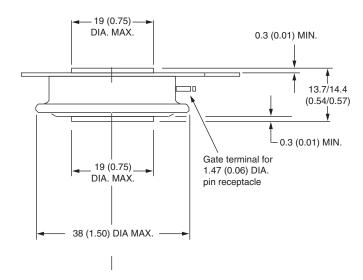


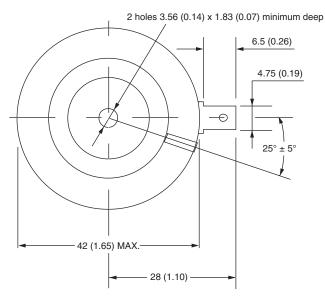
TO-200AB (A-PUK)

DIMENSIONS in millimeters (inches)

Anode to gate

Creepage distance: 7.62 (0.30) minimum Strike distance: 7.12 (0.28) minimum





Quote between upper and lower pole pieces has to be considered after application of mounting force (see thermal and mechanical specification)



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